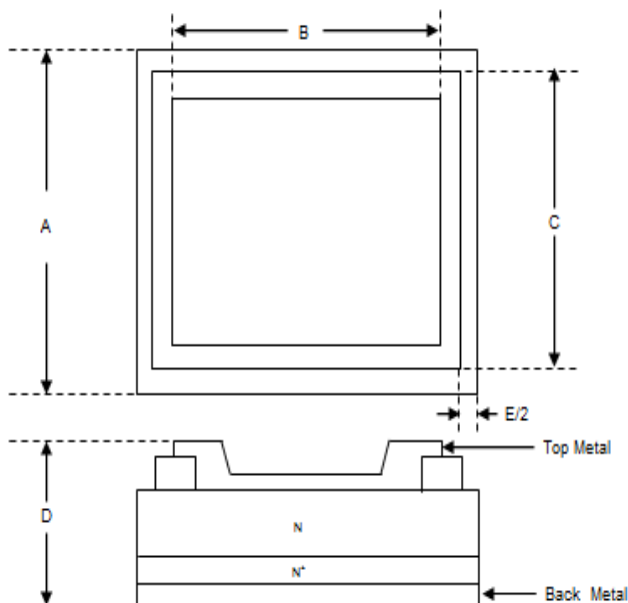


### Trench Schottky Barrier Diode Wafer (TSBD)



Item	Dimensions	
	um	mil
Die Size (A)	1705	67
Top Metal Pad Size (B)	1540	60.6
Passivation Seal (C)	1645	64.8
Wafer Thickness (D)	260	10.2
Scribe Line Width (E)	60	2.36
Other Informations		
Wafer Size	6"	
Gross Die	5500	
Top Metal	Ag	
Back Metal	Ag	

Electrical Characteristics @TA=25°C				
Item	Symbol	Spec. Limit	Die Sort	Unit
Maximum Repetitive Peak Reverse Voltage @0.1mA	$V_{RRM}$	80	85	V
Maximum Average Forward Rectified Current	$I_O$	10	-	A
Forward Voltage Drop, @ $I_F=3A$ @ $I_F=5A$ @ $I_F=10A$	$V_F$	- 0.59 0.75	0.52 -	V
Maximum Reverse Current at Rated $V_{RRM}$	$I_R$	50	25	$\mu A$
Peak Forward Surge Current, 8.3ms Single Half Sine-wave Superimposed on Rated Load (JEDEC Method)	$I_{FSM}$	100	-	A
Operating Temperature Range	$T_J$	-50 to +150	-	°C
Storage Temperature Range	$T_{STG}$	-50 to +150	-	°C